



LTM8022 50LD 9mm X 11.25mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

The LTM8022 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0362	Barium Compounds	7727-43-7		
				Filler Substances (Silica Crystalline)	-		
				Copper Metal	7440-50-8		
				Copper Compounds	1328-53-6		
				Ecotoxic substances	7439-92-1		
				Gold metal or alloy	7440-57-5		
				Nickel	7440-02-0		
2	Solder Paste	Alloy	0.0065	Sn	7440-31-5	0.00620	95.0
				Sb	7440-36-0	0.00033	5.0
3	Passive/Active Components		0.2942	Capacitor	-	0.02259	100
				Resistor	-	0.00033	
				Inductor	-	0.26286	
				Diode	-	0.00845	
4	Active Ics	Silicon	0.0023	Silicon	7440-21-3	0.00225	100
5	Wire	Gold	0.0001	Au	7440-57-5	0.0000800	99.99
6	Encapsulation	Epoxy Resin	0.5495	Fused Silica	60676-86-0	0.42421	77.2
				Epoxy Resin	-	0.04891	8.9
				Phenol Resin	-	0.04891	8.9
				Crytalline Silica	14808-60-7	0.01649	3.0
				Carbon Black	1333-86-4	0.00275	0.5
				Metal Hydroxide	-	0.00824	1.5
Total Package Weight			0.8887				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts